

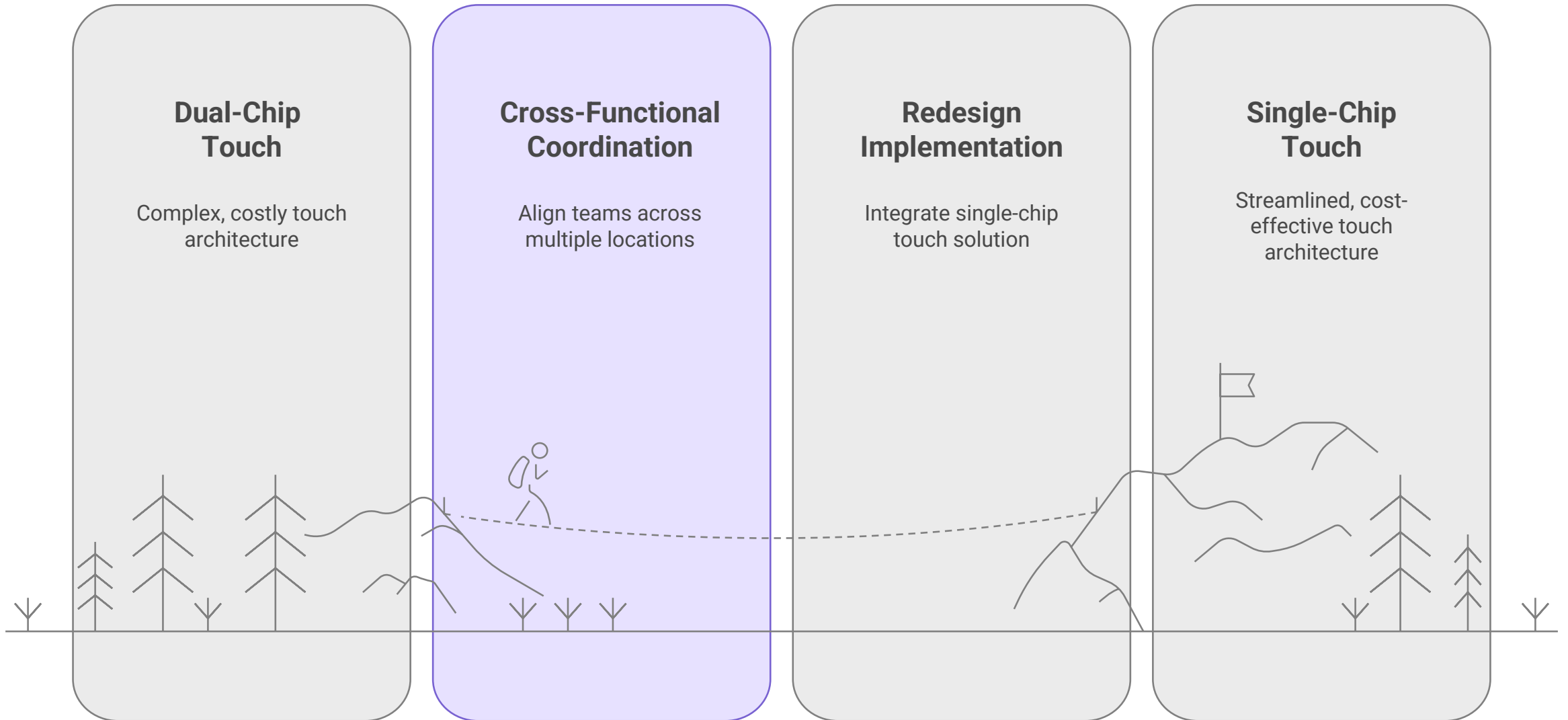
# Leadership in Portfolio-wide UI Touch Re-Design

User interface touch  
sensing redesign ●



Portfolio wide Multi product impact

# Touch Architecture Transformation



# Dual-chip Touch Architecture



## Pros



Reused Design



Legacy proven design



Stable production



## Cons



High cost

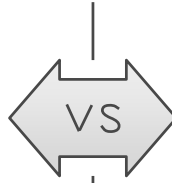


Suboptimal performance



Complex integration

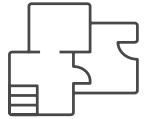
# Single-chip Touch Architecture



Cost savings



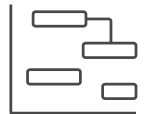
Improved performance



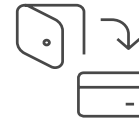
Streamlined integration



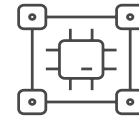
Team leadership



Project management

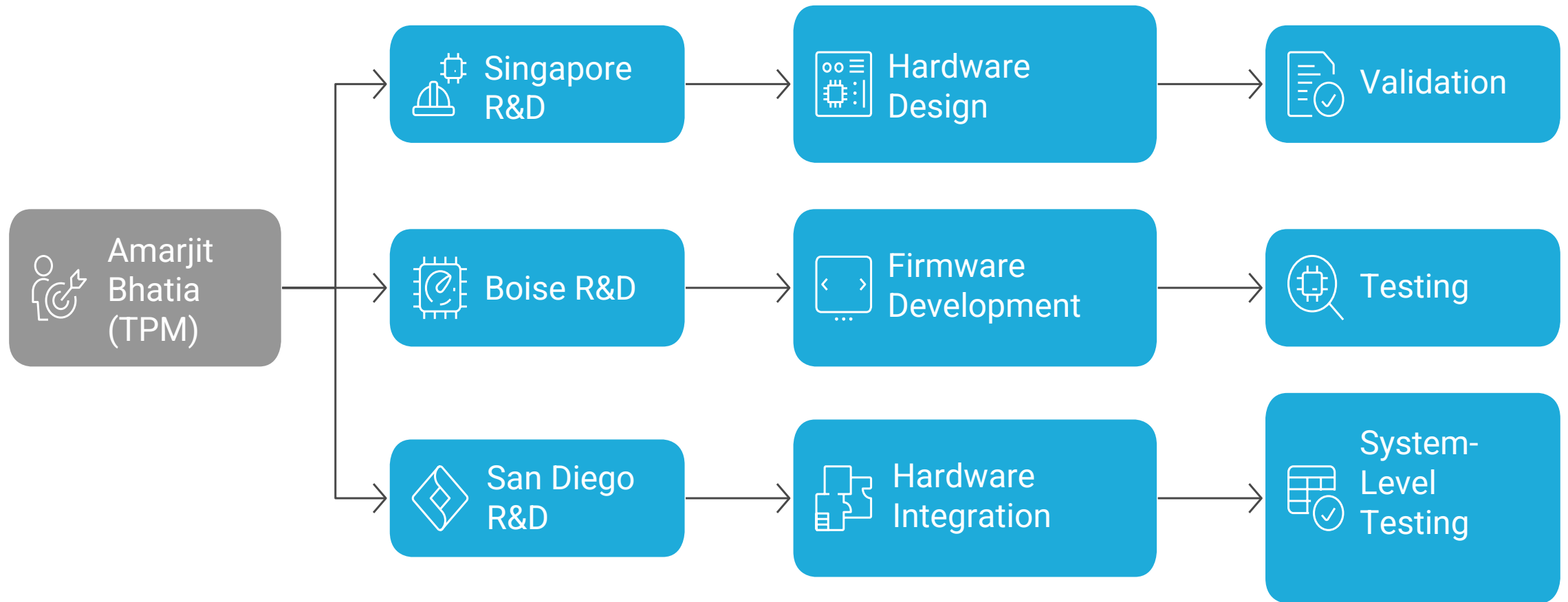


Initial investment



Technical challenges

# Project Coordination Flowchart



# Communication Strategies



## Regular Meetings

Weekly meetings to discuss progress and coordinate activities.

1



## Shared Documentation

Centralized repository for all project-related documents.

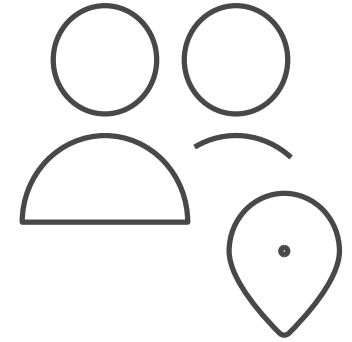
2



## Communication Tools

Collaboration tools to facilitate real-time communication.

3

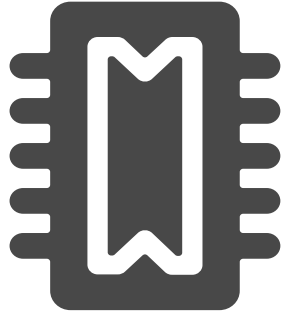


## On-site Visits

Visiting different locations to ensure alignment.

4

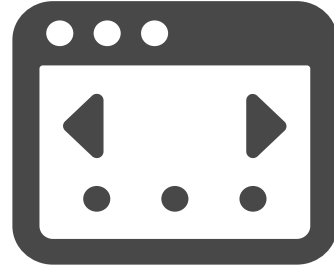
# Project Challenges and Solutions



## Hardware Design

Designing a single chip required careful consideration of power consumption, processing speed, and memory capacity.

1



## Firmware Development

Developing firmware required a deep understanding of the hardware architecture and touch algorithms.

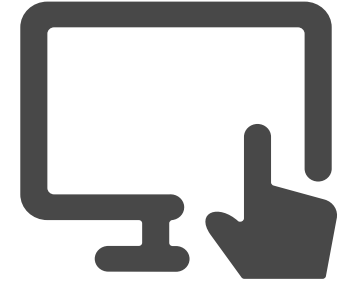
2



## Regulatory Compliance

Working with regulatory labs to get the new design through compliance and certification testing.

3

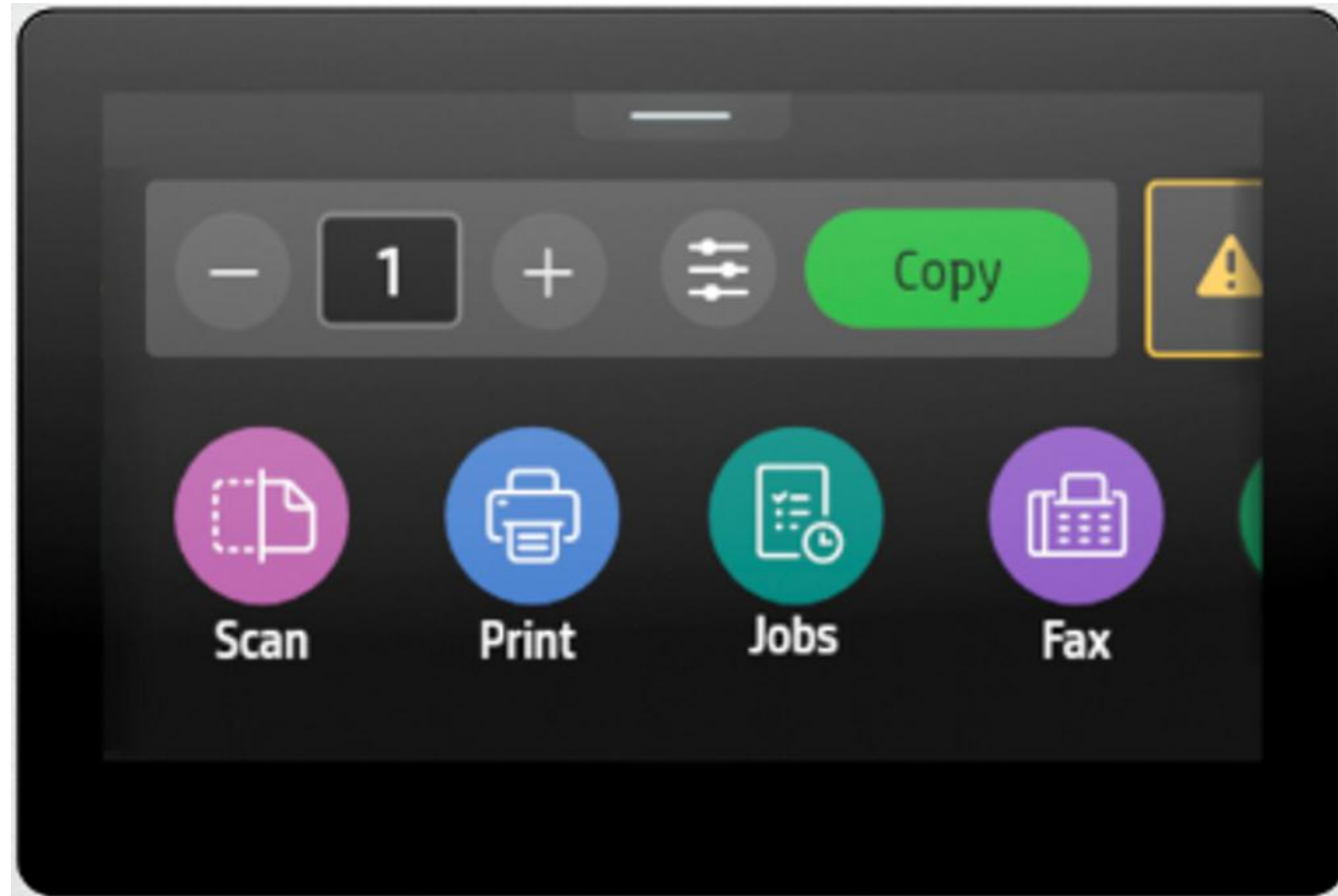


## Touch Performance Testing

Working with the supplier to perform robotic calibration and code tuning.

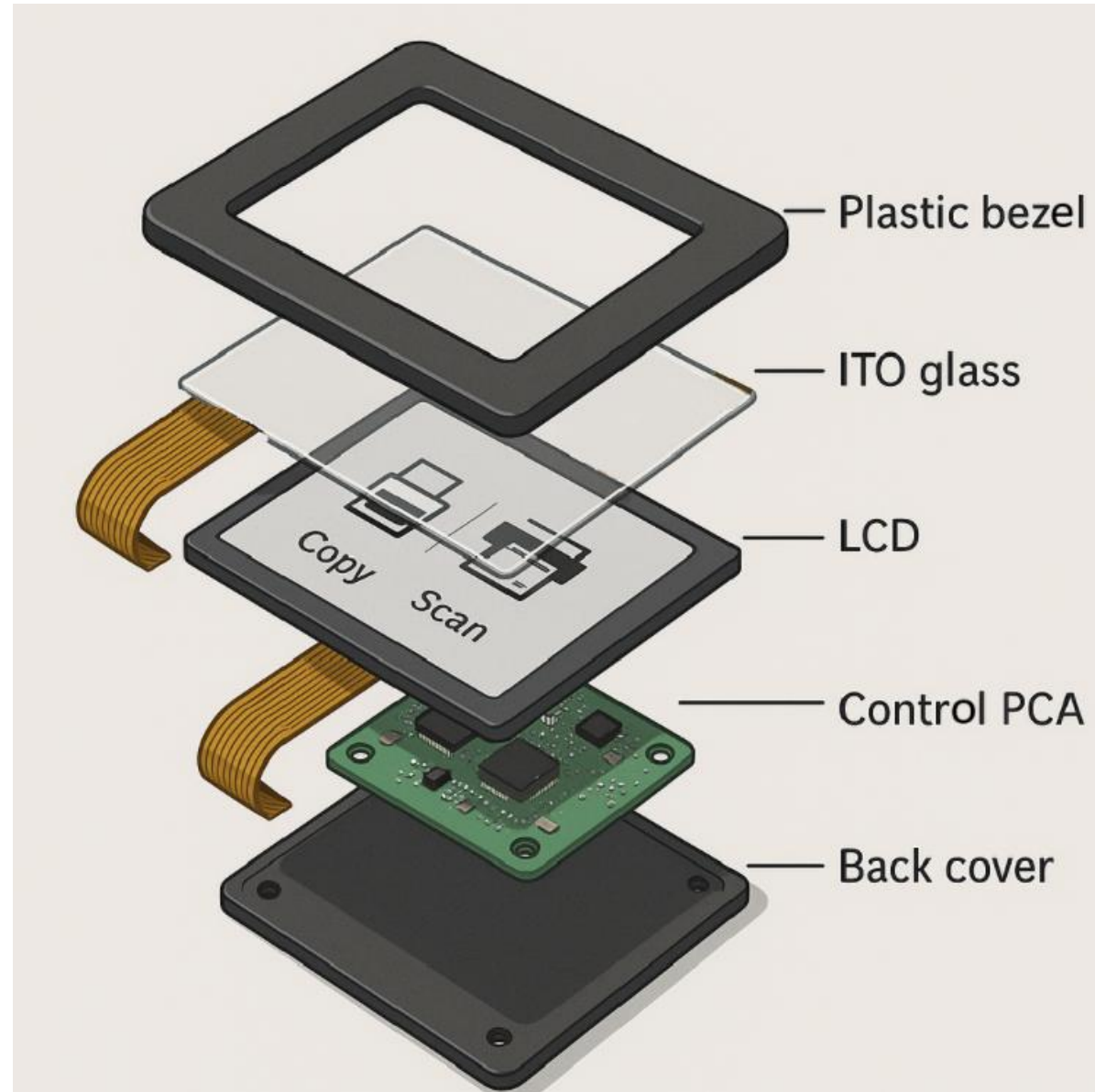
4

# Change Details Touch Sensing Architecture Change





# Control Panel Architecture



# Lead Re-Architecture of Control Panel Touch Sensing



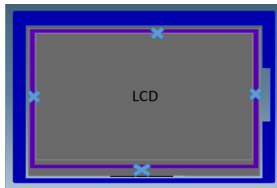
Sustainable solution



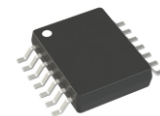
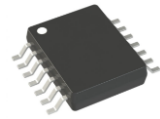
Complexity reduction



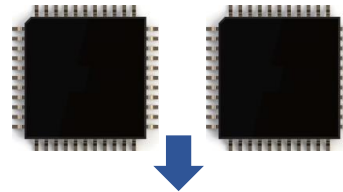
Lower cost implementation



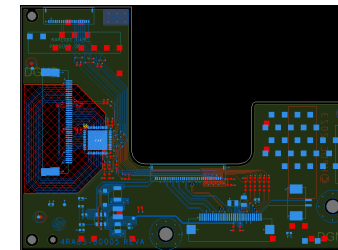
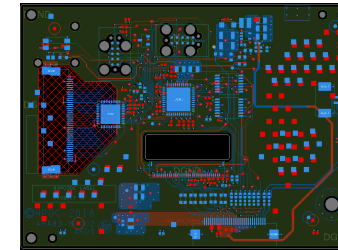
Cost reduce  
Display to ITO  
Glass attach



Remove Back  
bias buffers



Two chip to single  
chip Solution  
Hardware and  
Firmware redesign

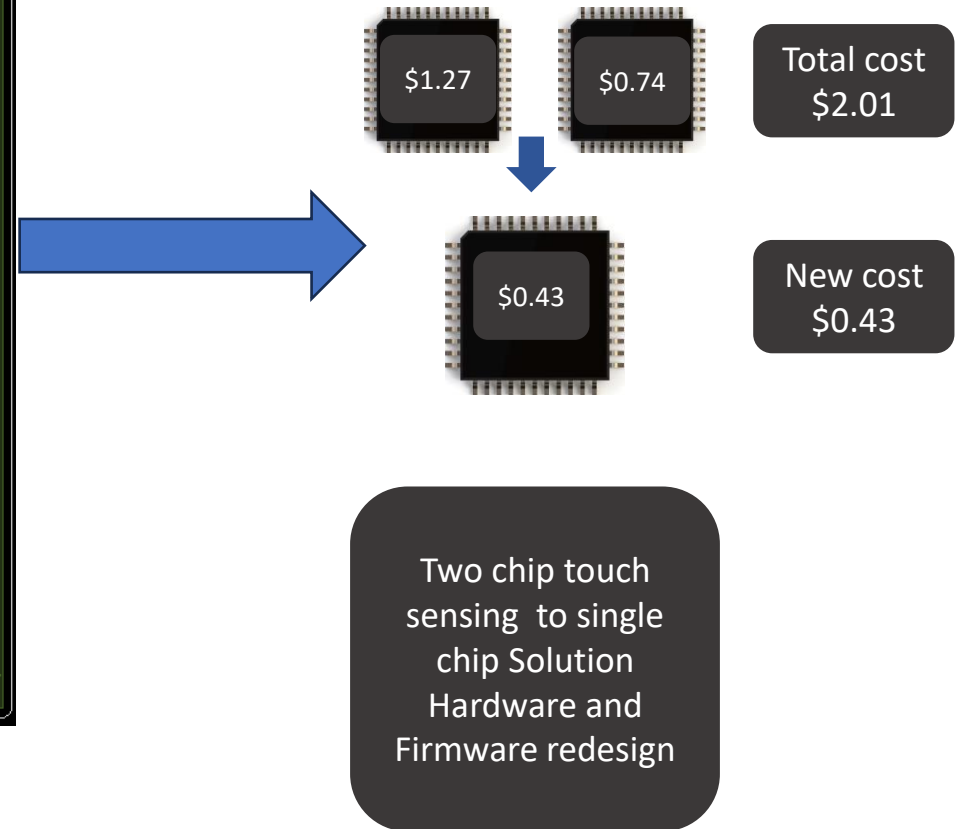
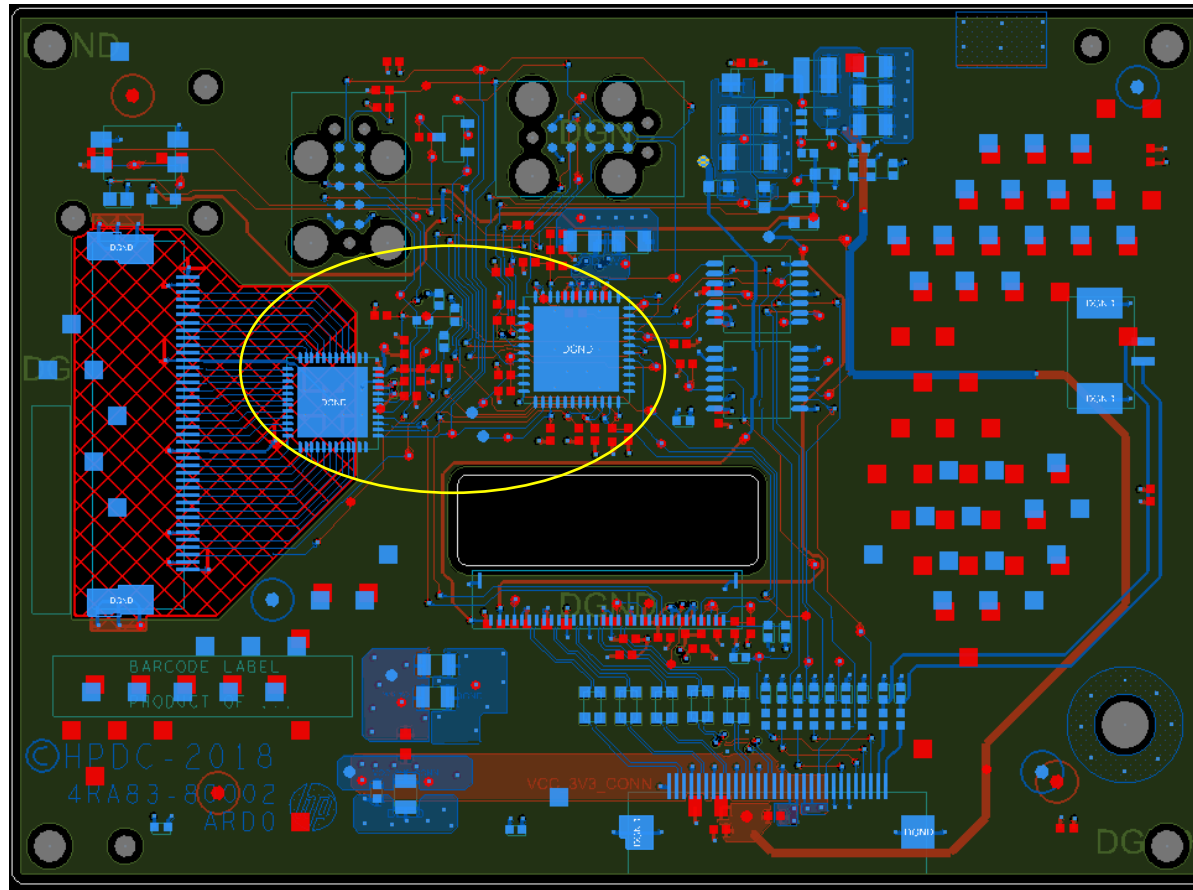


Redesign PCB to  
smaller size

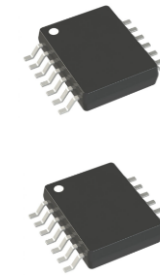
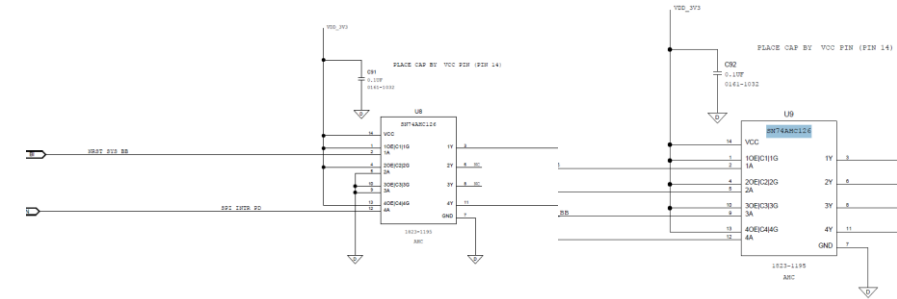
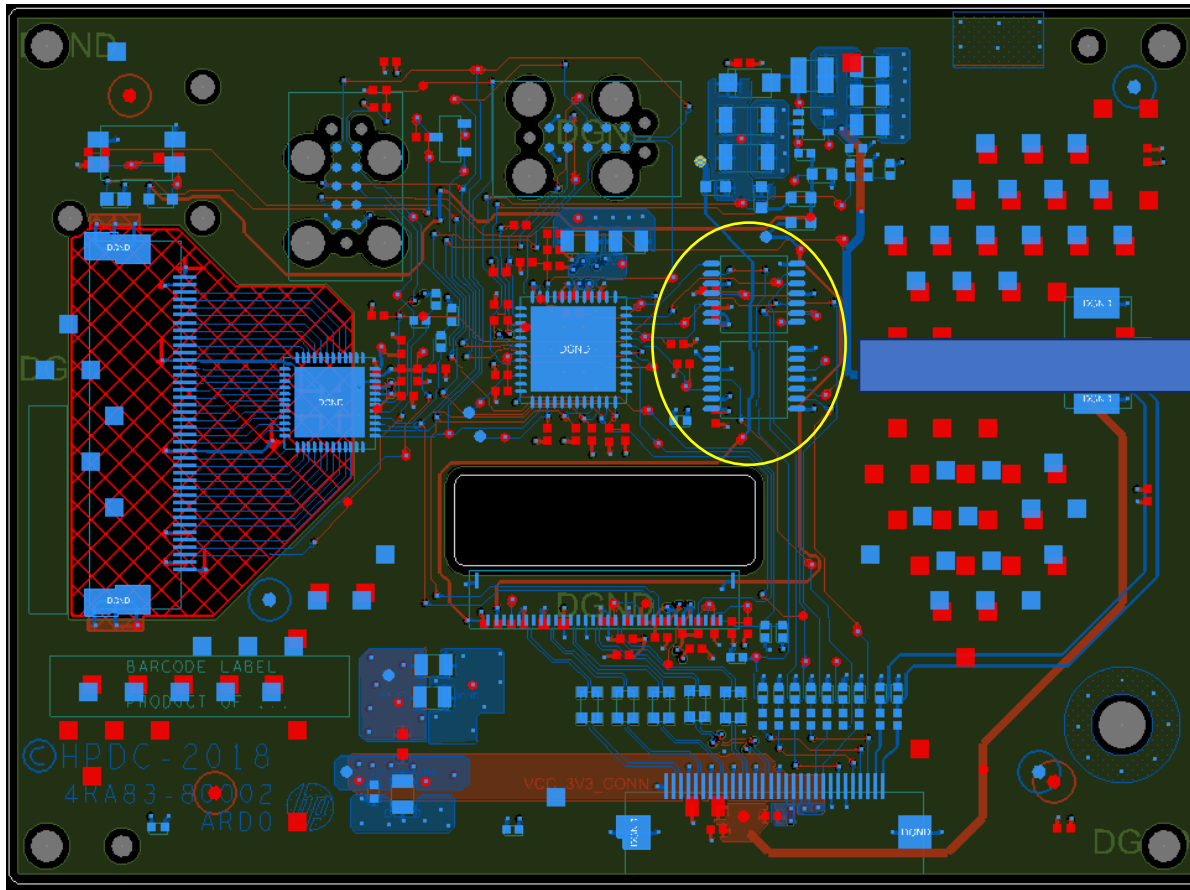


Qualify lower  
cost speaker  
supplier

# Capacitive Touch 2 Microcontroller to Single Microcontroller | \$1.58/unit savings

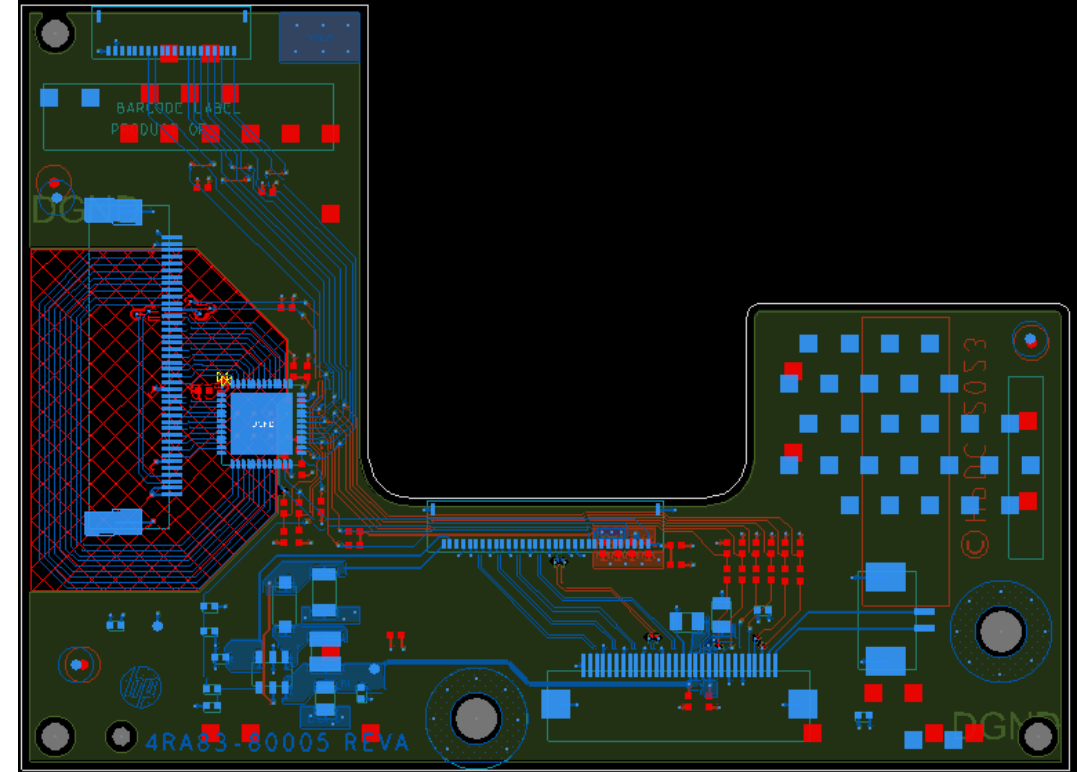
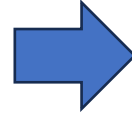
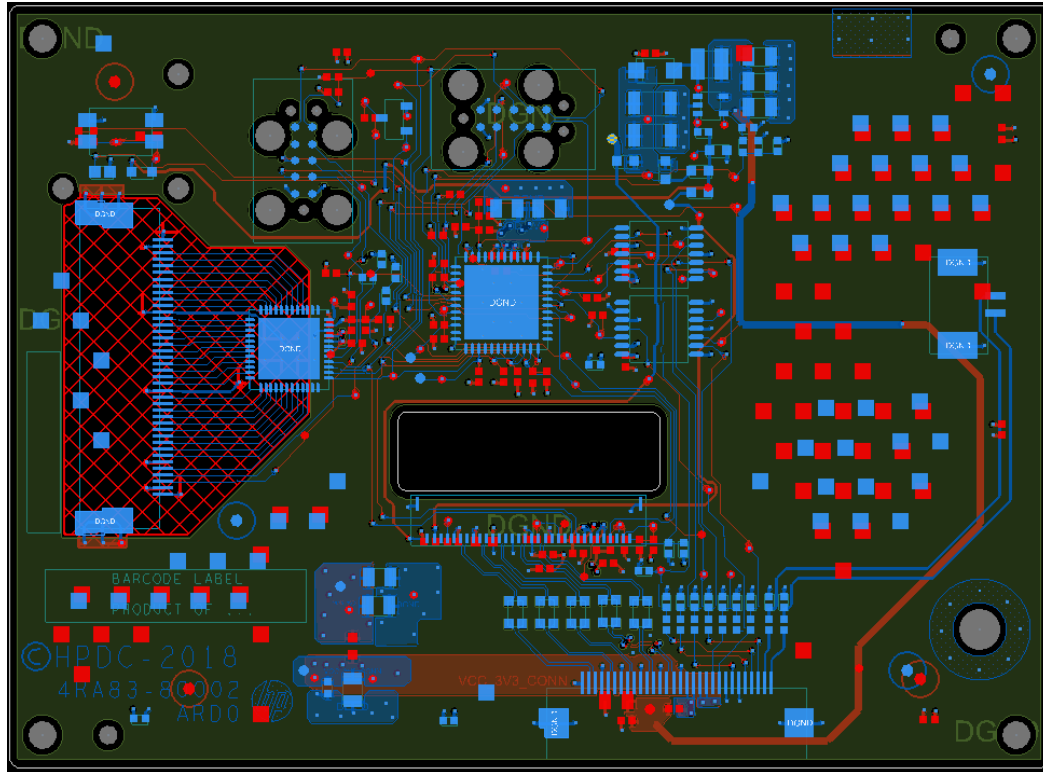


# Remove Back Bias Buffers | \$0.20/unit savings



Remove Back Bias buffers while maintaining good signal Integrity

# Redesign PCB to smaller nested PCB | Saving \$0.38/unit



# Use ITO adhesive to attach Display | \$0.10/unit



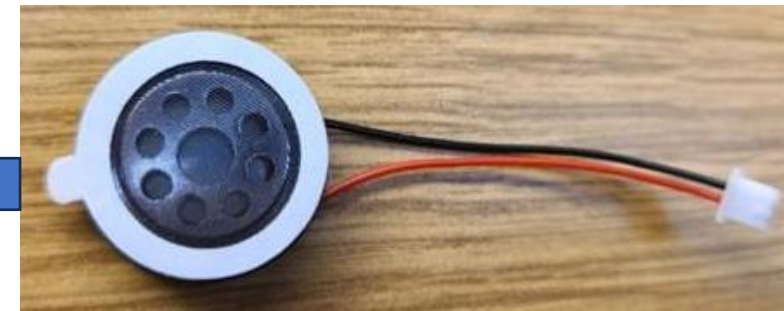
Touchscreen Adhesive enlarged by adding material to the inner dimension

Part Number	Description	unit cost	qty	Ext. cost
3SJ05-00004	Adhesive - LCD	0.034	2	0.069
3SJ05-00005	Adhesive - LCD Side	0.015	2	0.029
			Savings	0.098

Worked with the ITO supplier to grow ITO attach area, removed 4 inner adhesive strips and direct attach the Display to ITO glass

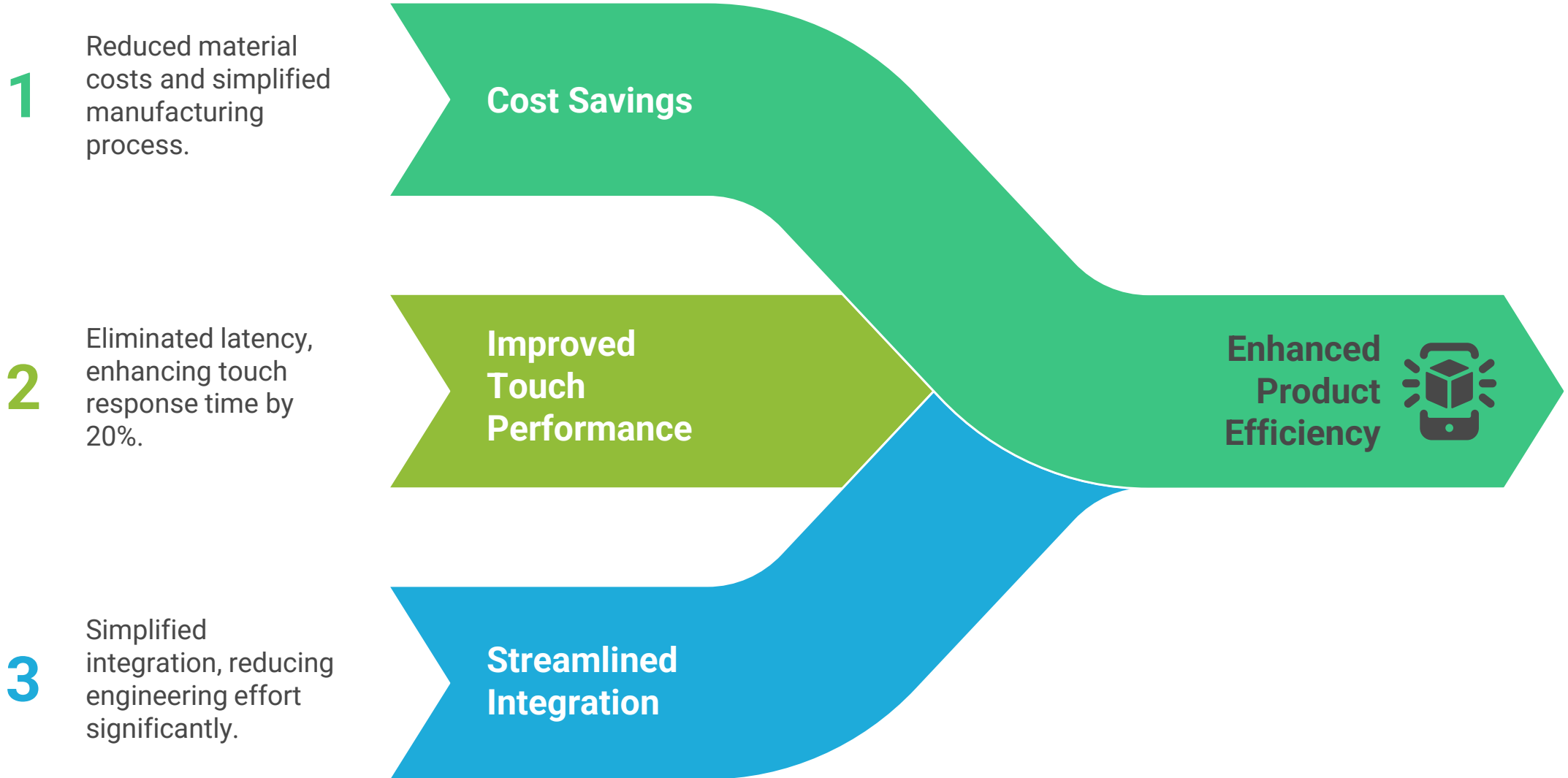


# Qualified Lower cost Speaker | \$0.14/unit



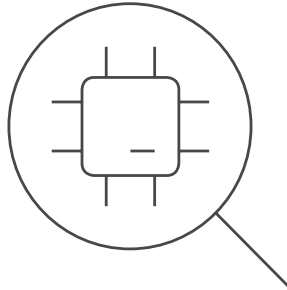
Collaborated with the supplier to design and qualify a speaker at a lower cost, while meeting the audio performance.

# Single-Chip Architecture Benefits





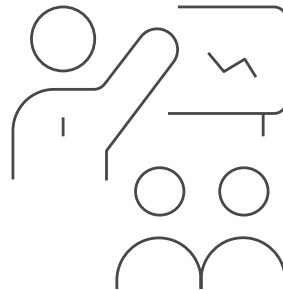
# Deployment to Manufacturing



## Testing Procedures

Developed new testing procedures to ensure quality standards.

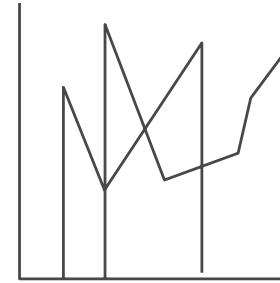
1



## Personnel Training

Provided training to manufacturing personnel on new processes.

2

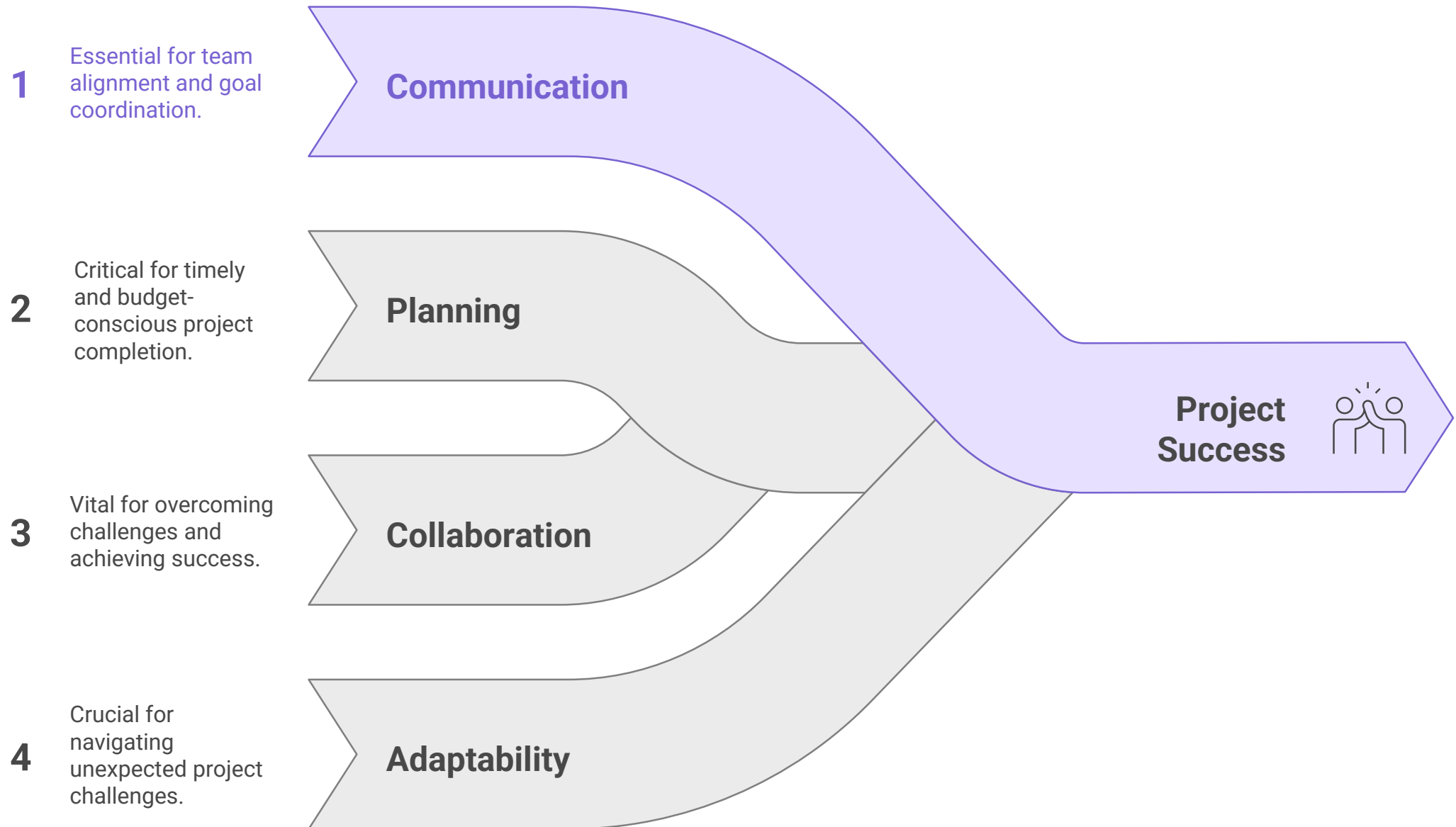


## Yield Monitoring

Closely monitored production yields to address manufacturing issues.

3

# Demonstrated Pathways to Project Excellence



# Journey to Project Success

